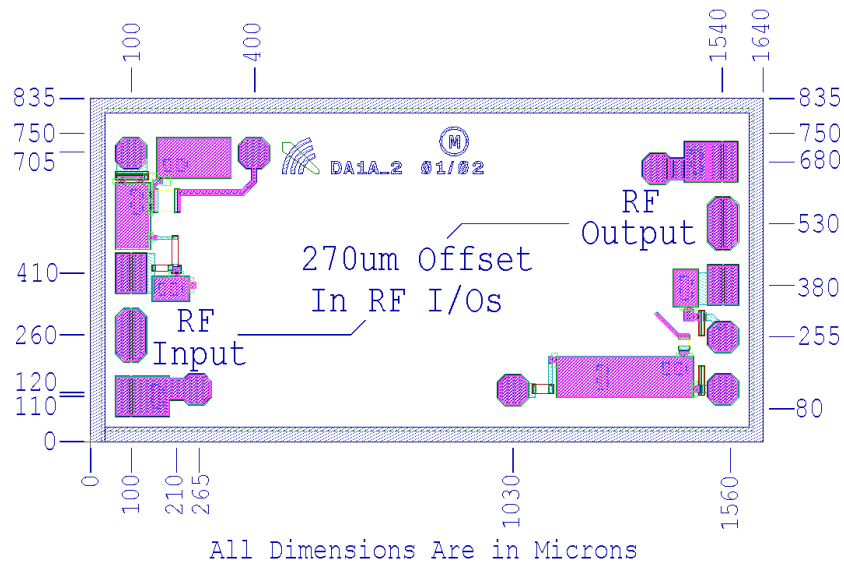
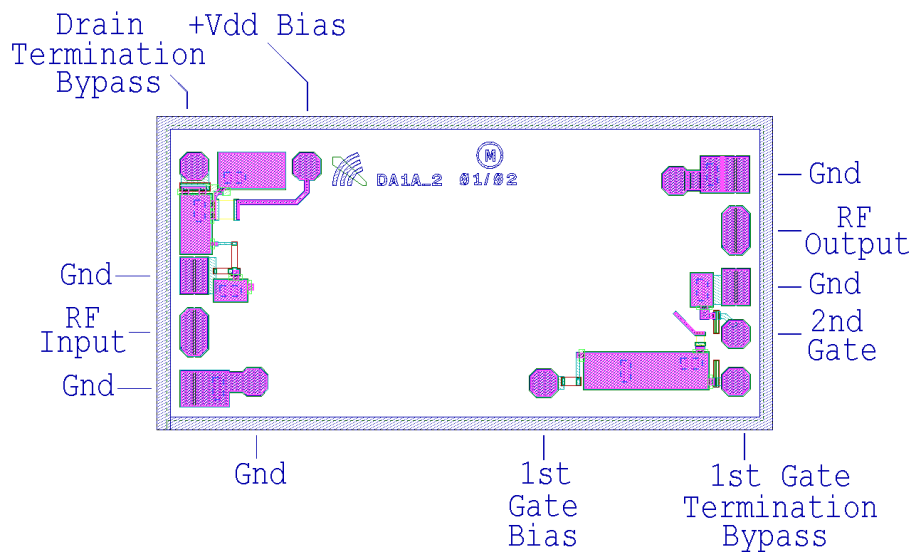


## MMA027AA Bonding Diagram

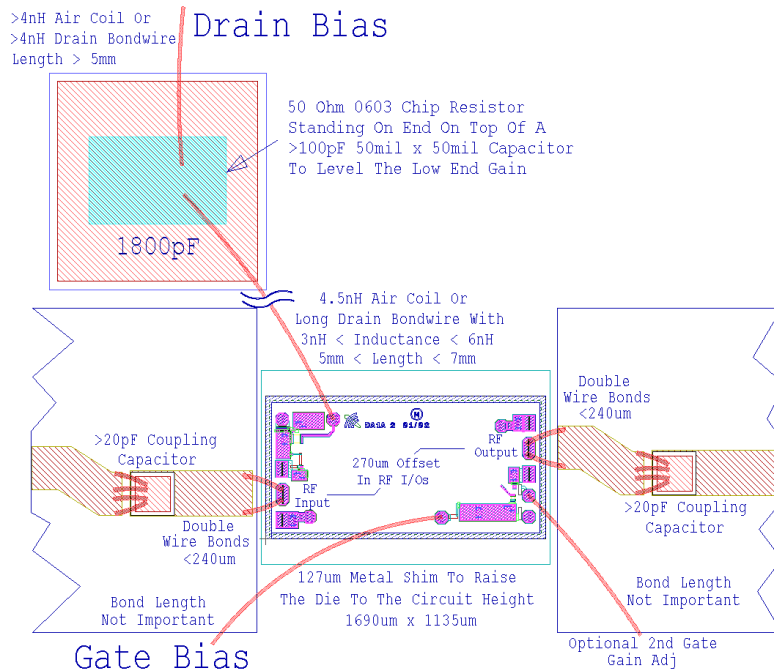


**Figure 1. Die size**

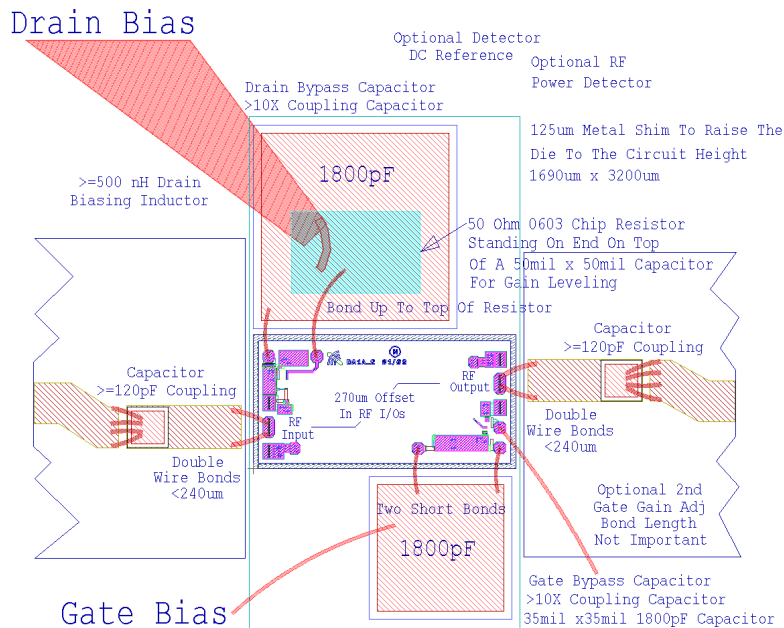


**Figure 2. Pad Locations and Pad Descriptions**

Chip size: 1640x835 $\mu$ m (64.6x32.9mil)  
 Chip size tolerance:  $\pm$ 5 $\mu$ m (0.2mil)  
 Chip thickness: 100  $\pm$ 10 $\mu$ m (4  $\pm$ 0.4mil)  
 Pad dimensions: 80x80 $\mu$ m (3.1x3.1mil)



**Figure 3.2 - 30GHz bonding diagram**



**Figure 4. 40MHz - 30GHz bonding diagram**

### Pick-up and Chip Handling

This MMIC has exposed air bridges on the top surface. **Do not pick up chip with vacuum on the die center**; handle from edges or use a collet.

### Thermal Heat Sinking

To avoid damage and for optimum performance, you must observe the maximum channel temperature and ensure adequate heat sinking.

### ESD Handling and Bonding

**This MMIC is ESD sensitive**; preventive measures should be taken during handling, die attach, and bonding.

**Epoxy die attach is recommended.** Please review our application note [MM-APP-0001](#) GaAs MMIC handling and die attach recommendations, on our website for more handling, die attach and bonding information.



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